

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Pey-Yuan Lee	04/23/2004
Feng-Liang Lai	04/23/2004
Cheng-Kuo Chu	04/23/2004
Chi-Shen Lo	04/23/2004

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	10822960

CORRESPONDENCE DATA

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Correspondent Name: Haynes and Boone, LLP

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NAME OF SUBMITTER:

David M. O'Dell

Total Attachments: 3

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PATENT

REEL: 015315 FRAME: 0954

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ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|----------------|----|-----------------------------|
| (1) | Pey-Yuan Lee | of | Tainan City, Taiwan, R.O.C. |
| (2) | Feng-Liang Lai | of | Tainan City, Taiwan, R.O.C. |
| (3) | Cheng-Kuo Chu | of | Tainan City, Taiwan, R.O.C. |
| (4) | Chi-Shen Lo | of | Tainan City, Taiwan, R.O.C. |

have invented certain improvements in

CARRYOVER REDUCTION IN MULTIPLE CDSEM LINE MATCHING

for which we have executed an application for Letters Patent of the United States of America,

 of even date filed herewith; and
 X filed on April 13, 2004 and assigned application number 10/822,960; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and

testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

First Inventor Name: Pey-Yuan Lee
Residence Address: _____

Dated: ✓ 4/23/2004

✓ pylee
Inventor Signature

Dated: _____

Witness Signature
Witness Name: _____

Second Inventor Name: Feng-Liang Lai
Residence Address: _____

Dated: ✓ 4/23/2004

✓ FL Lai
Inventor Signature

Dated: _____

Witness Signature
Witness Name: _____

Third Inventor Name: Cheng-Kuo Chu
Residence Address:

Dated: ✓ 4/23/2004

✓ C.K. Chu
Inventor Signature

Dated: _____

Witness Signature

Witness Name: _____

Fourth Inventor Name: Chi-Shen Lo
Residence Address:

Dated: 4/23/2004

CSL
Inventor Signature

Dated: _____

Witness Signature

Witness Name: _____

R-61212.1